

# INTERNATIONAL STANDARD

## NORME INTERNATIONALE



**Printed boards and printed board assemblies – Design and use –  
Part 6-4: Land pattern design – Generic requirements for dimensional drawings  
of surface mounted components (SMD) from the viewpoint of land pattern  
design**

**Cartes imprimées et cartes imprimées équipées – Conception et utilisation –  
Partie 6-4: Conception de la zone de report – Exigences génériques pour les  
dessins dimensionnels de composants montés en surface (CMS) du point  
de vue de la conception de la zone de report**



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IEC Central Office  
3, rue de Varembe  
CH-1211 Geneva 20  
Switzerland

Tel.: +41 22 919 02 11  
[info@iec.ch](mailto:info@iec.ch)  
[www.iec.ch](http://www.iec.ch)

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## CONTENTS

FOREWORD.....	4
1 Scope.....	6
2 Normative references .....	6
3 Terms, definitions and symbols.....	6
4 Applicable SMDs .....	8
5 Requirements .....	9
5.1 Figures and dimensional symbols .....	9
5.2 Common requirements .....	9
5.2.1 General .....	9
5.2.2 Requirements for solder joint fillet design .....	9
5.2.3 Requirements for courtyard design .....	10
5.2.4 Height parameters .....	10
5.2.5 Bottom view.....	12
5.2.6 Detail view.....	12
5.2.7 Distinguish between metal and resin.....	12
5.2.8 Consistency of various dimensions .....	12
5.2.9 The relation between a land pattern and an element placement position.....	13
5.2.10 Coplanarity .....	14
5.3 Requirements for a specific SMD .....	14
5.3.1 General .....	14
5.3.2 End-terminal type .....	14
5.3.3 Gull-wing terminals type, inward L-shaped ribbon terminals type and under-body L type.....	18
5.3.4 Bottom surface terminal type and flat lug terminals type .....	30
6 Supplementary dimensions.....	39
Bibliography.....	40
Figure 1 – Example of the dimensional relationship to the drawings of SMDs, the land pattern design and the after soldering state .....	12
Figure 2 – Example of dimensional consistency for an asymmetrical SMD .....	13
Figure 3 – Example of the direction of recommendation for land pattern position of an asymmetrical SMD.....	14
Figure 4 - Influence of good and bad (after soldering) coplanarity .....	14
Figure 5 – Example of the dimensional relationship between the drawings of components with rectangular terminals and the land pattern design .....	16
Figure 6 – Example of the dimensional notations for a component with rectangular terminals .....	17
Figure 7 – Example of the dimensional notations for cylindrical components with end cap terminals .....	18
Figure 8 – Example of the dimensional relationship between the drawings of gull-wing terminals type and the land pattern design.....	19
Figure 9 – Example of the dimensional notations for gull-wing terminals type (QFP) .....	20
Figure 10 – Details of terminal (case 1) .....	21
Figure 11 – Details of terminal (case 2) .....	22
Figure 12 – Details of terminal (case 3) .....	22

Figure 13 – Details of terminal (case 4) .....	23
Figure 14 – Details of terminal (case 5) .....	23
Figure 15 – Example of the dimensional relationship between the drawings of inward L-shaped ribbon terminals type and the land pattern design.....	24
Figure 16 – Example of the dimensional notations for inward L-shaped ribbon terminals type .....	25
Figure 17 – Example of the dimensional notations for under-body L type .....	26
Figure 18 – Terminal shape expansion drawing of under-body L type (capacitor).....	27
Figure 19 – Example of the dimensional notations for a connector .....	28
Figure 20 – The cross-sectional a-a detail (terminal shape) of Figure 18, side view .....	29
Figure 21 – Example of the drawing showing the moving range (lock lever open state) .....	29
Figure 22 – Example of the upper surface cap constitution .....	29
Figure 23 – Example of the dimensional relationship between the drawings of a BGA and the land pattern design.....	31
Figure 24 – Example of the dimensional notations for BGA.....	32
Figure 25 – Example of details of solder balls (side view) .....	33
Figure 26 – Example of the dimensional relationship between the drawings of QFN and the land pattern design .....	34
Figure 27 – Example of the dimensional notations for bottom surface terminals .....	36
Figure 28 – Example of the dimensional relationship between the drawings of flat lug terminals type and the land pattern design.....	38
Figure 29 – Example of the dimensional notations for flat lug terminals type .....	39
Figure 30 – Example of the recommended dimensions in the tray .....	39
Table 1 – Reference symbols used in this document.....	7

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

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**PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES –  
DESIGN AND USE –**
**Part 6-4: Land pattern design – Generic requirements for dimensional  
drawings of surface mounted components (SMD) from the viewpoint of  
land pattern design**

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International Standard IEC 61188-6-4 has been prepared by IEC technical committee 91: Electronic assembly technology.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
91/1561/FDIS	91/1572/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61188 series, published under the general title *Printed boards and printed board assemblies – Design and use*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

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## PRINTED BOARDS AND PRINTED BOARD ASSEMBLIES – DESIGN AND USE –

### Part 6-4: Land pattern design – Generic requirements for dimensional drawings of surface mounted components (SMD) from the viewpoint of land pattern design

#### 1 Scope

This part of IEC 61188 specifies generic requirements for dimensional drawings of SMD from the viewpoint of land pattern design.

The purpose of this document is to prevent land pattern design issues caused by lack of information and/or misuse of the information from SMD outline drawing as well as to improve the utilization of IEC 61188 series.

This document is applicable to the SMD of semiconductor devices and electrical components.

#### 2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60194, *Printed board design, manufacture and assembly – Terms and definitions*

IEC 60194-2, *Printed board design, manufacture and assembly – Vocabulary – Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies*

#### 3 Terms, definitions and symbols

For the purposes of this document, the terms and definitions given in IEC 60194 and IEC 60194-2 apply, and the reference symbols are shown in Table 1.

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